

leads that correspond to the bonding pads, the leads being located on opposite sides of the semiconductor chip with the bonding pads therebetween;

wires electrically connecting the bonding pads to the leads; and

a molding resin encapsulating the semiconductor chip, leads and wires, wherein:

the leads include a plurality of general leads and at most four stable leads;

the at most four stable leads are electrically connected to the bonding pads via the wires, extend toward the semiconductor chip, and are physically affixed to the semiconductor chip; and

the general leads are electrically connected to the bonding pads by way of the wires, and separated from the semiconductor chip, thereby coming into no physical contact with the semiconductor chip.

2. The LOC type semiconductor package as claimed in claim 1, wherein:

the general leads include general inner leads encapsulated in the molding resin and general outer leads extending from the molding; and

the stable leads include stable inner leads encapsulated in the molding resin and stable outer leads extending from the molding resin.

3. The LOC type semiconductor package as claimed in claim 2, wherein an adhesive member is on the portion of the surface of the semiconductor chip, corresponding to the end of each of the stable inner leads, to fix the end of the stable inner lead onto the surface of the semiconductor chip.

4. The LOC type semiconductor package as claimed in claim 3, wherein the surface area of the end of the stable inner lead coming into contact with the adhesive member is